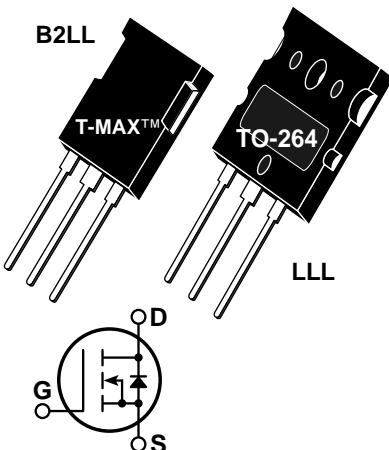


## POWER MOS 7™

Power MOS 7™ is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7™ by significantly lowering  $R_{DS(ON)}$  and  $Q_g$ . Power MOS 7™ combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with APT's patented metal gate structure.



- Lower Input Capacitance
- Increased Power Dissipation
- Lower Miller Capacitance
- Easier To Drive
- Lower Gate Charge,  $Q_g$
- Popular T-MAX™ or TO-264 Package

### MAXIMUM RATINGS

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT10035	UNIT
$V_{DSS}$	Drain-Source Voltage	1000	Volts
$I_D$	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	28	Amps
$I_{DM}$	Pulsed Drain Current ①	112	
$V_{GS}$	Gate-Source Voltage Continuous	$\pm 30$	
$V_{GSM}$	Gate-Source Voltage Transient	$\pm 40$	Volts
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	690	Watts
	Linear Derating Factor	5.52	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_L$	Lead Temperature: 0.063" from Case for 10 Sec.	300	
$I_{AR}$	Avalanche Current ① (Repetitive and Non-Repetitive)	28	Amps
$E_{AR}$	Repetitive Avalanche Energy ①	50	
$E_{AS}$	Single Pulse Avalanche Energy ④	3000	mJ

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$BV_{DSS}$	Drain-Source Breakdown Voltage ( $V_{GS} = 0\text{V}$ , $I_D = 250\mu\text{A}$ )	1000			Volts
$I_{D(on)}$	On State Drain Current ② ( $V_{DS} > I_{D(on)} \times R_{DS(on)}$ Max, $V_{GS} = 10\text{V}$ )	28			Amps
$R_{DS(on)}$	Drain-Source On-State Resistance ② ( $V_{GS} = 10\text{V}$ , $0.5 I_{D(\text{Cont.})}$ )			0.350	Ohms
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{DS} = V_{DSS}$ , $V_{GS} = 0\text{V}$ )			100	$\mu\text{A}$
	Zero Gate Voltage Drain Current ( $V_{DS} = 0.8 V_{DSS}$ , $V_{GS} = 0\text{V}$ , $T_C = 125^\circ\text{C}$ )			500	
$I_{GSS}$	Gate-Source Leakage Current ( $V_{GS} = \pm 30\text{V}$ , $V_{DS} = 0\text{V}$ )			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage ( $V_{DS} = V_{GS}$ , $I_D = 2.5\text{mA}$ )	3		5	Volts

 CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

USA	405 S.W. Columbia Street	Bend, Oregon 97702-1035	Phone: (541) 382-8028	FAX: (541) 388-0364
EUROPE	Chemin de Magret	F-33700 Mérignac - France	Phone: (33) 5 57 92 15 15	FAX: (33) 5 56 47 97 61

## DYNAMIC CHARACTERISTICS

APT10035 B2LL - LLL

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{ MHz}$		5185		pF
$C_{oss}$	Output Capacitance			900		
$C_{rss}$	Reverse Transfer Capacitance			144		
$Q_g$	Total Gate Charge ③	$V_{GS} = 10V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = I_{D[\text{Cont.}]} @ 25^\circ\text{C}$		183		nC
$Q_{gs}$	Gate-Source Charge			24		
$Q_{gd}$	Gate-Drain ("Miller") Charge			117		
$t_{d(on)}$	Turn-on Delay Time	$V_{GS} = 15V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = I_{D[\text{Cont.}]} @ 25^\circ\text{C}$ $R_G = 0.6\Omega$		12		ns
$t_r$	Rise Time			11		
$t_{d(off)}$	Turn-off Delay Time			38		
$t_f$	Fall Time			9		

## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$I_S$	Continuous Source Current (Body Diode)			28	Amps
$I_{SM}$	Pulsed Source Current ① (Body Diode)			112	
$V_{SD}$	Diode Forward Voltage ② ( $V_{GS} = 0V, I_S = -I_{D[\text{Cont.}]}^*$ )			1.3	Volts
$t_{rr}$	Reverse Recovery Time ( $I_S = -I_{D[\text{Cont.}]}^*$ , $dI_S/dt = 100A/\mu\text{s}$ )		1156		ns
$Q_{rr}$	Reverse Recovery Charge ( $I_S = -I_{D[\text{Cont.}]}^*$ , $dI_S/dt = 100A/\mu\text{s}$ )		28.7		$\mu\text{C}$
$dv/dt$	Peak Diode Recovery $dv/dt$ ⑤			10	V/ns

## THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.18	°C/W
$R_{\theta JA}$	Junction to Ambient			40	

① Repetitive Rating: Pulse width limited by maximum junction temperature.

③ See MIL-STD-750 Method 3471

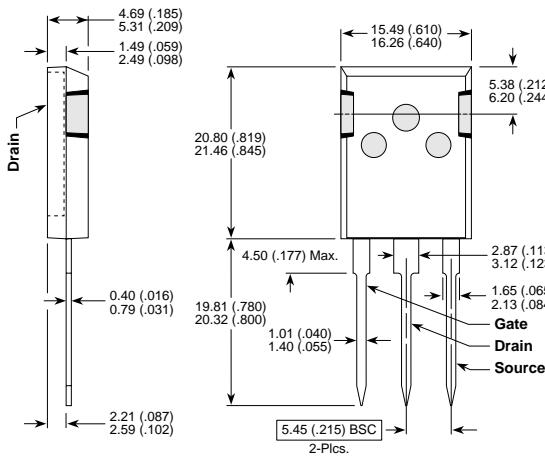
② Pulse Test: Pulse width < 380  $\mu\text{s}$ , Duty Cycle < 2%

④ Starting  $T_j = +25^\circ\text{C}$ ,  $L = 7.65\text{mH}$ ,  $R_G = 25\Omega$ , Peak  $I_L = 28\text{A}$

⑤  $dv/dt$  numbers reflect the limitations of the test circuit rather than the device itself.  $I_S \leq -I_{D[\text{Cont.}]}^*$ ,  $di/dt \leq 700\text{A}/\mu\text{s}$ ,  $V_R \leq V_{DSS}$ ,  $T_j \leq 150^\circ\text{C}$

APT Reserves the right to change, without notice, the specifications and information contained herein.

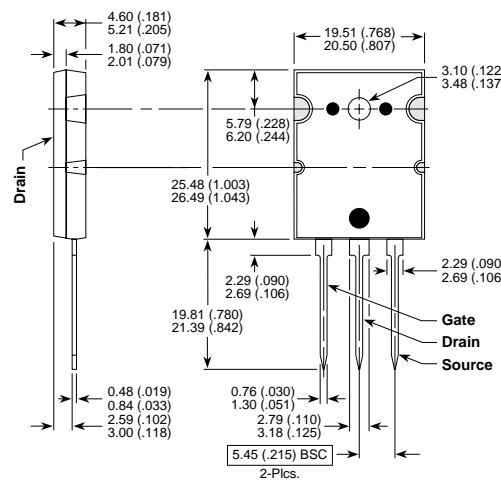
**T-MAX™ (B2) Package Outline**



These dimensions are equal to the TO-247 without the mounting hole.

Dimensions in Millimeters and (Inches)

**TO-264 (L) Package Outline**



Dimensions in Millimeters and (Inches)